

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:  
K. OKAJIMA, et al.

Serial No.: To Be Assigned

Art Unit: To Be Assigned

Filed: Concurrently herewith

Examiner: To Be Assigned

For: Method For Forming Solder-Resist Film

INFORMATION DISCLOSURE STATEMENT  
PURSUANT TO 37 C.F.R. §§ 1.56, 1.97 and 1.98

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450



Sir:

In compliance with the dictates of 37 C.F.R. §§ 1.56, 1.97 and 1.98, Applicants hereby submit an Information Disclosure Statement.

It is respectfully requested that the Examiner consider this reference and indicate such consideration by enclosing an appropriately initialed copy of the enclosed form PTO-1449 with the next communication from the Patent Office.

Respectfully submitted,

Donald E. Townsend  
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Date: July 31, 2003

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| <b>INFORMATION DISCLOSURE CITATION</b><br><br><i>(Use several sheets if necessary)</i> | Atty. Docket No.<br>M&M-067-USA-P | Serial No.<br>To be assigned |
|  | Applicants:<br>K. Okajima, et al. |                              |
|  | Filing Date:<br>July 31, 2003     | Group<br>To be assigned      |

**U.S. PATENT DOCUMENTS**

| *Examiner Initial | Document Number | Date | Name | Class | Subclass | Filing Date If Appropriate |
|-------------------|-----------------|------|------|-------|----------|----------------------------|
|                   |                 |      |      |       |          |                            |
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**FOREIGN PATENT DOCUMENTS**

|  | Document Number | Date | Country | Class | Subclass | Translation |    |
|--|-----------------|------|---------|-------|----------|-------------|----|
|  |                 |      |         |       |          | Yes         | No |
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**OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Page, Etc.)**

|                     |                            |   |
|---------------------|----------------------------|---|
| <div>EXAMINER</div> | <div>DATE CONSIDERED</div> | Japanese Patent Laid-Open No. 222103 (2001) |
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\*Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.